

L Number	Hits	Search Text	DB	Time stamp
1	54309	(Chemical adj mechanical adj polish\$3 ) or CMP or planariz\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/20 10:14
36	54		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/20 10:29
43	721	( (Chemical adj mechanical adj polish\$3 ) or CMP or planariz\$5) and (pattern near3 density)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/20 10:27
50	316	(( (Chemical adj mechanical adj polish\$3 ) or CMP or planariz\$5) and (pattern near3 density) ) and (etch\$3 with pattern)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/20 10:27
57	42	(( (Chemical adj mechanical adj polish\$3 ) or CMP or planariz\$5) and (pattern near3 density) ) and (etch\$3 with pattern) ) and (thickness with variation\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/20 10:28
64	54	(( (Chemical adj mechanical adj polish\$3 ) or CMP or planariz\$5) and (pattern near3 density) ) and (etch\$3 with pattern) ) and (device near3 region\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/20 10:29
71	91	(( (( (Chemical adj mechanical adj polish\$3 ) or CMP or planariz\$5) and (pattern near3 density) ) and (etch\$3 with pattern) ) and (thickness with variation\$1)) or ((( (Chemical adj mechanical adj polish\$3 ) or CMP or planariz\$5) and (pattern near3 density) ) and (etch\$3 with pattern) ) and (device near3 region\$1) )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/20 10:29
85	7	((((( (Chemical adj mechanical adj polish\$3 ) or CMP or planariz\$5) and (pattern near3 density) ) and (etch\$3 with pattern) ) and (thickness with variation\$1)) or ((( (Chemical adj mechanical adj polish\$3 ) or CMP or planariz\$5) and (pattern near3 density) ) and (etch\$3 with pattern) ) and (device near3 region\$1) )) and (test\$3 with region\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/20 10:45
92	84	((((( (Chemical adj mechanical adj polish\$3 ) or CMP or planariz\$5) and (pattern near3 density) ) and (etch\$3 with pattern) ) and (thickness with variation\$1)) or ((( (Chemical adj mechanical adj polish\$3 ) or CMP or planariz\$5) and (pattern near3 density) ) and (etch\$3 with pattern) ) and (device near3 region\$1) )) not (((((( (Chemical adj mechanical adj polish\$3 ) or CMP or planariz\$5) and (pattern near3 density) ) and (etch\$3 with pattern) ) and (thickness with variation\$1)) or ((( (Chemical adj mechanical adj polish\$3 ) or CMP or planariz\$5) and (pattern near3 density) ) and (etch\$3 with pattern) ) and (device near3 region\$1) )) and (test\$3 with region\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/20 10:46